



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE5206-2G	Issued	05. May 2021
MA#	MA001209578		
Package	PG-TO263-7-1	Weight*	1538.64 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.039	0.72	0.72	7175	7175
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		526	
	non noble metal	copper	7440-50-8	808.613	52.56	52.63	525535	526219
wire	non noble metal	aluminium	7429-90-5	3.409	0.22	0.22	2216	2216
encapsulation	inorganic material	zinc oxide	1314-13-2	5.855	0.38		3806	
	miscellaneous	miscellaneous	-	23.422	1.52		15222	
	plastics	epoxy resin	-	87.831	5.71		57084	
	inorganic material	silicon dioxide	60676-86-0	468.433	30.44	38.05	304446	380558
lead finish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8473	8473
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	138	139
solder	non noble metal	tin	7440-31-5	0.188	0.01		122	
	noble metal	silver	7440-22-4	0.235	0.02		153	
	non noble metal	lead	7439-92-1	8.965	0.58	0.61	5827	6102
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.90	6.91	69028	69118
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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